ASSOCIATION CONNECTING ELECTROMICS INDUSTRIES INDUSTRIES International and Pan-Ameri	nnockburn, Illinois. A	ll rights reserved ur ations.	der both This doc level par	ument is a the decla	declaration aration en	n of the substance compasses all low	es within the manufactur ver level materials for w	rer listed ite hich the ma	em. Note: if th unufacturer ha	e item is an as s engineering	sembly with lower responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form 7   http://www.ipc.org/IPC-175x Distribution			* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials				als and Mfg	ls and Mfg Information			
Supplier Information												
mpany name* Company unique ID				Unique ID Authority				Response Date*				
onsemi	emi							2024-05-21				
Contact Name	ne Title - Contact			Phone - Contact*				Email - Contact*				
Product-Env-Stewards	ct-Env-Stewards Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
uthorized Representative* Title - Representative				Phone - Representative*				Email - Representative*				
Product-Env-Stewards Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requester Item Number Mr	fr Item Number	Mfr Item Name		Effect	ive Date	Version	Manufacturing Site		/eight*	UOM	Unit Type	
	CP4306AADZZZA N1TBG			ies 2024-0	05-21	MY1		10	).01	mg	Each	
Manufacturing Proccess Information												
Terminal Plating / Grid Array Material	Ferminal Plating / Grid Array Material Terminal Base Alloy		STD-020 MSL Rating	Pe	eak Proces	s Body Temperat	ture Max Time at Peak	Temperatu	re Number	of Reflow Cyc	les	
Matte Tin (Sn) - annealed CU Alloy 1				20	50	С	30	second	s 3			
Comments												
level 1 - maximum time at peak temperature dur	ing soldering is 10-3	0 seconds										
For more information regarding material compo	sition please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted	
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the
Supplier Digital Signature Ra	stislav Drska	Le			

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.1	mg	Supplier	Silicon (Si)	7440-21-3		0.1	mg
Die Attach	0.24	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		0.048	mg
			Supplier	Silver (Ag)	7440-22-4		0.192	mg
Lead Frame	3.71	mg	Supplier	Silver (Ag)	7440-22-4		0.0371	mg
			Supplier	Tin (Sn)	7440-31-5		0.0093	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0082	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0093	mg
			Supplier	Copper (Cu)	7440-50-8		3.6462	mg
Mold Compound-Black	5.0	mg	Supplier	Epoxy and Phenolic Resin	40216-08-8		0.4	mg
			Supplier	Carbon Black (C)	1333-86-4		0.025	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.1	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		4.325	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.15	mg
Plating	0.29	mg	Supplier	Tin (Sn)	7440-31-5		0.29	mg
Wire Bond - Au	0.67	mg	Supplier	Gold (Au)	7440-57-5		0.67	mg